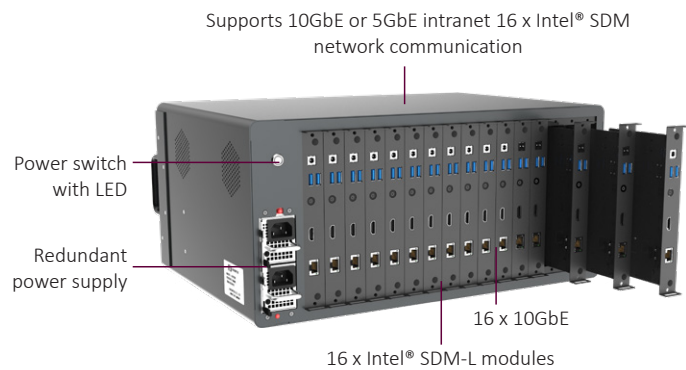
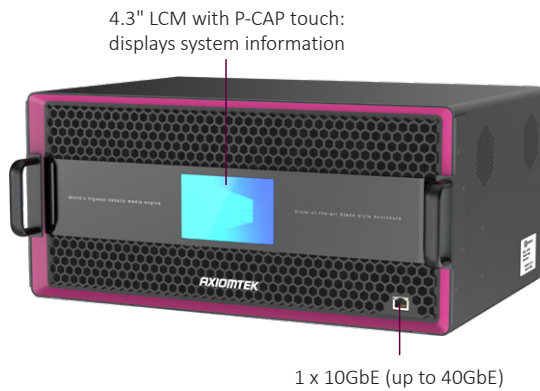


DSP820 NEW

A High-Density Edge AI Agent Swarm Server



8K Ultra HD



Redundant Power



DDR5



10G-40G
Ethernet



Hot-Swap



Easy
Maintenance



Modularized
Design

Features

- Supports 16 hot-swappable Intel® SDM modules
- Supports external 10GbE (up to 40GbE) network connectivity
- Supports internal 10GbE or 5GbE networking for communication among up to 16 Intel® SDM modules
- Enables distributed Multi-AI Agent processing with independent and fault-isolated computing nodes
- Advanced media playback solution supporting 16 HDMI 8K60 outputs
- Integrates a 4.3-inch touchscreen for centralized system monitoring and management

Specifications

Motherboard	Smart display module: SDM530L	
CPU	Intel® Core™ Ultra 7/5 processors (Meteor Lake-H) 125H/155H	
Chipset	SoC integrated	
System Memory	Dual DDR5-5200 SO-DIMM, up to 96GB per SDM	
System I/O Outlet	Ethernet	16 x 10GbE LAN (Intel® E610) (rear I/O) 1 x 40GbE LAN (front I/O) supporting 10GbE intranet communication for 16 SDM modules
	Display	16 x HDMI output 2.1 (8K @ 60Hz)
	USB	32 x USB 3.2 Gen 2 Type-A
	Power Button	16 x power button
Storage	1 x M.2 Key M 2230 slot (PCIe Gen 4 x4)/per SDM 1 x M.2 Key M 2280 slot (PCIe Gen 4 x4 and SATA signals)/per SDM	
Internal LAN Switch Board and Docking Board	Supports 10GbE intranet communication among 16 x SDM modules 16 x PCIe x8 slots (for SDM modules)	
Internal SDM Edge Connector/ per SDM	1 x HDMI 2.1 1 x DisplayPort 1.4 1 x USB 3.2 Gen 2 x1 1 x 10GbE LAN 1 x Serial TX/RX 1 x I ² C 1 x PCIe x1	
Expansion Interface	1 x M.2 Key M 2280 slot/per SDM (PCIe Gen 4 x4 and SATA signals) for HDMI capture card	
TPM	dTPM2.0	
BIOS	American Megatrends Inc. UEFI (Unified Extensible Firmware Interface)	
Watchdog Timer	255 levels, 1 to 255 sec.	
Power Input	Through SDM golden finger +12V and +3.3VSB or +12V DC-in through front I/O Note: front-panel DC input and the redundant power adapter cannot be used simultaneously.	
Power Consumption (Max.)	1 x 960W, redundant power supply	
Operating Temperature	0°C to +30°C (+32°F to +86°F)	
Relative Humidity	10% to 95% relative humidity, non-condensing	
Construction	Steel chassis	
Dimensions (W x D x H)	480 x 223 x 325 mm (18.89" x 8.75" x 12.87")	
Weight (net/gross)	10 kg (22.04 lbs)/11 kg (24.25 lbs)	
OS Support	Windows® 11 IoT LTSC, Linux	

*Specifications and certifications may vary based on different requirements.

Ordering Information

DSP820-SDM530L-I5-125H (P/N: TBC)	DSP820 with SDM530L Intel® Core™ Ultra 5 processors (Meteor Lake-H) 125H, 16 LAN, 32 USB 3.2, and 16 HDMI 2.1
DSP820-SDM530L-I7-155H (P/N: TBC)	DSP820 with SDM530L Intel® Core™ Ultra 7 processors (Meteor Lake-H) 155H, 16 LAN, 32 USB 3.2, and 16 HDMI 2.1

Dimensions

